

# SGFM101C-D2 THRU SGFM108C-D2

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# SGFM101C-D2 THRU SGFM108C-D2

## 10.0A Surface Mount Super Fast Rectifiers-50-600V

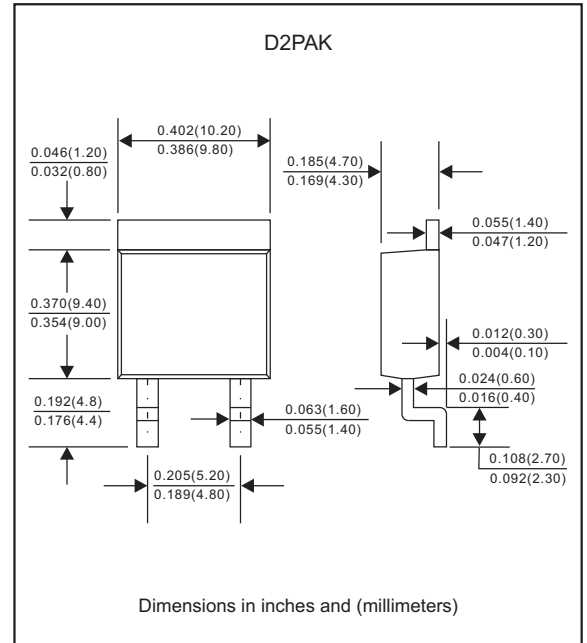
### Features

- Batch process design, excellent power dissipation offers better reverse leakage current and thermal resistance.
- High current capability.
- Super fast recovery time for switching mode application.
- High surge current capability.
- Glass passivated chip junction.
- Lead-free parts meet environmental standards of MIL-STD-19500/228
- Suffix "-H" indicates Halogen free parts, ex. SGFM101C-D2-H.

### Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, TO-263 / D2PAK
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Mounting Position : Any
- Weight : Approximated 1.46 gram

### Package outline



### Maximum ratings and Electrical Characteristics (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.1	$I_o$			10.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC method)	$I_{FSM}$			150	A
Reverse current	$V_R = V_{RRM} T_J = 25^{\circ}\text{C}$	$I_R$			5.0	$\mu\text{A}$
	$V_R = V_{RRM} T_J = 125^{\circ}\text{C}$				50	
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	$C_j$		80		pF
Storage temperature		$T_{STG}$	-65		+175	$^{\circ}\text{C}$

SYMBOLS	$V_{RRM}^{*1}$ (V)	$V_{RMS}^{*2}$ (V)	$V_R^{*3}$ (V)	$V_F^{*4}$ (V)	$t_{rr}^{*5}$ (ns)	Operating temperature $T_J$ ( $^{\circ}\text{C}$ )
SGFM101C-D2	50	35	50	0.95	35	-55 to +150
SGFM102C-D2	100	70	100			
SGFM104C-D2	200	140	200			
SGFM106C-D2	400	280	400	1.25		
SGFM108C-D2	600	420	600	1.70		

\*1 Repetitive peak reverse voltage

\*2 RMS voltage

\*3 Continuous reverse voltage

\*4 Maximum forward voltage@ $I_F=5.0\text{A}$

\*5 Maximum Reverse recovery time, note 1

Note 1. Reverse recovery time test condition,  $I_F=0.5\text{A}$ ,  $I_R=1.0\text{A}$ ,  $I_{RR}=0.25\text{A}$

# Rating and characteristic curves (SGFM101C-D2 THRU SGFM108C-D2)

FIG. 1 - FORWARD CURRENT DERATING CURVE

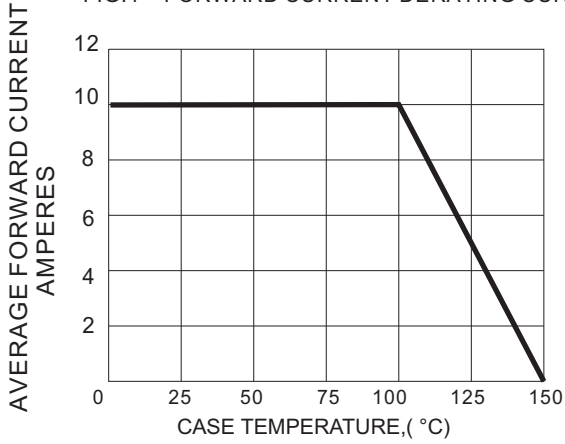


FIG. 2 - MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

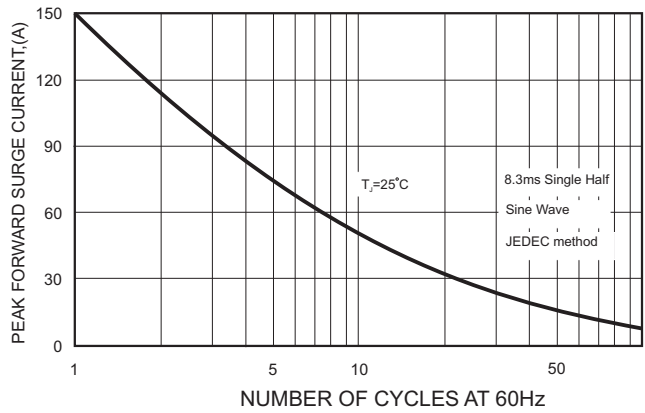


FIG. 3 - TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

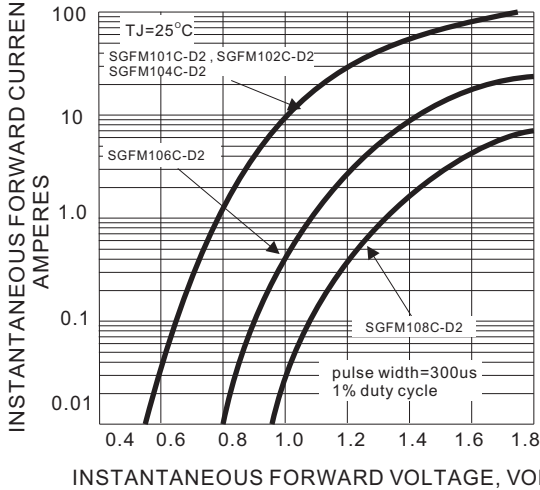


FIG. 4 - TYPICAL INSTANTANEOUS REVERSE CHARACTERISTICS

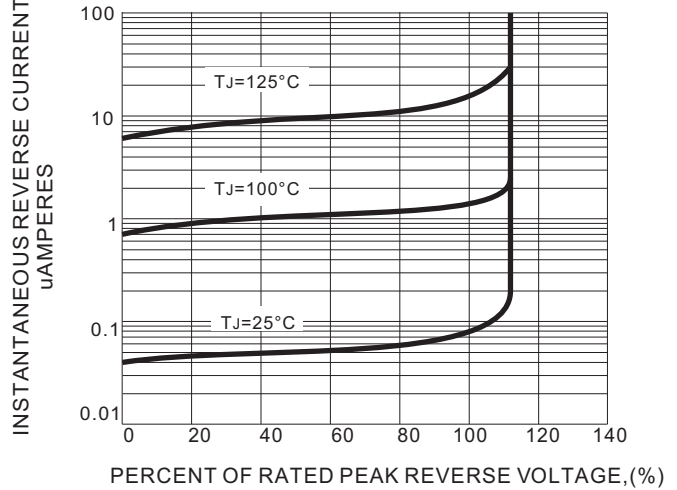


FIG. 5 - TYPICAL JUNCTION CAPACITANCE

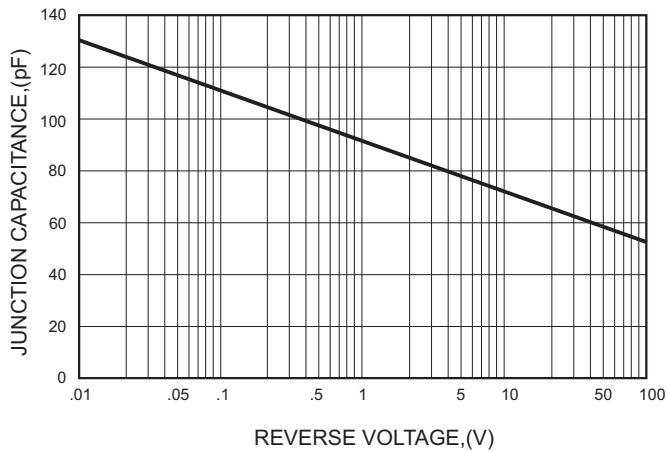
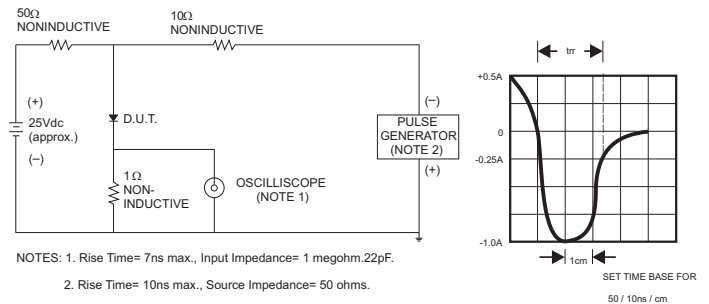
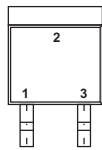
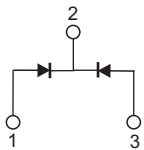


FIG. 6 - TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTIC



# SGFM101C-D2 THRU SGFM108C-D2

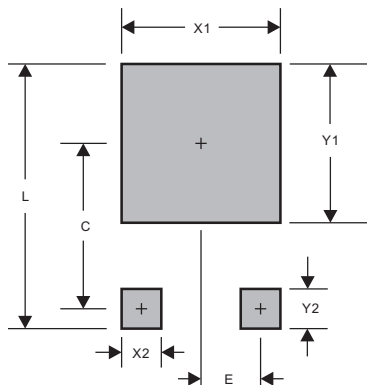
## Pinning information

Simplified outline	Symbol
	

## Marking

Type number	Marking code
SGFM101C-D2	SF101C
SGFM102C-D2	SF102C
SGFM104C-D2	SF104C
SGFM106C-D2	SF106C
SGFM108C-D2	SF108C

## Suggested solder pad layout

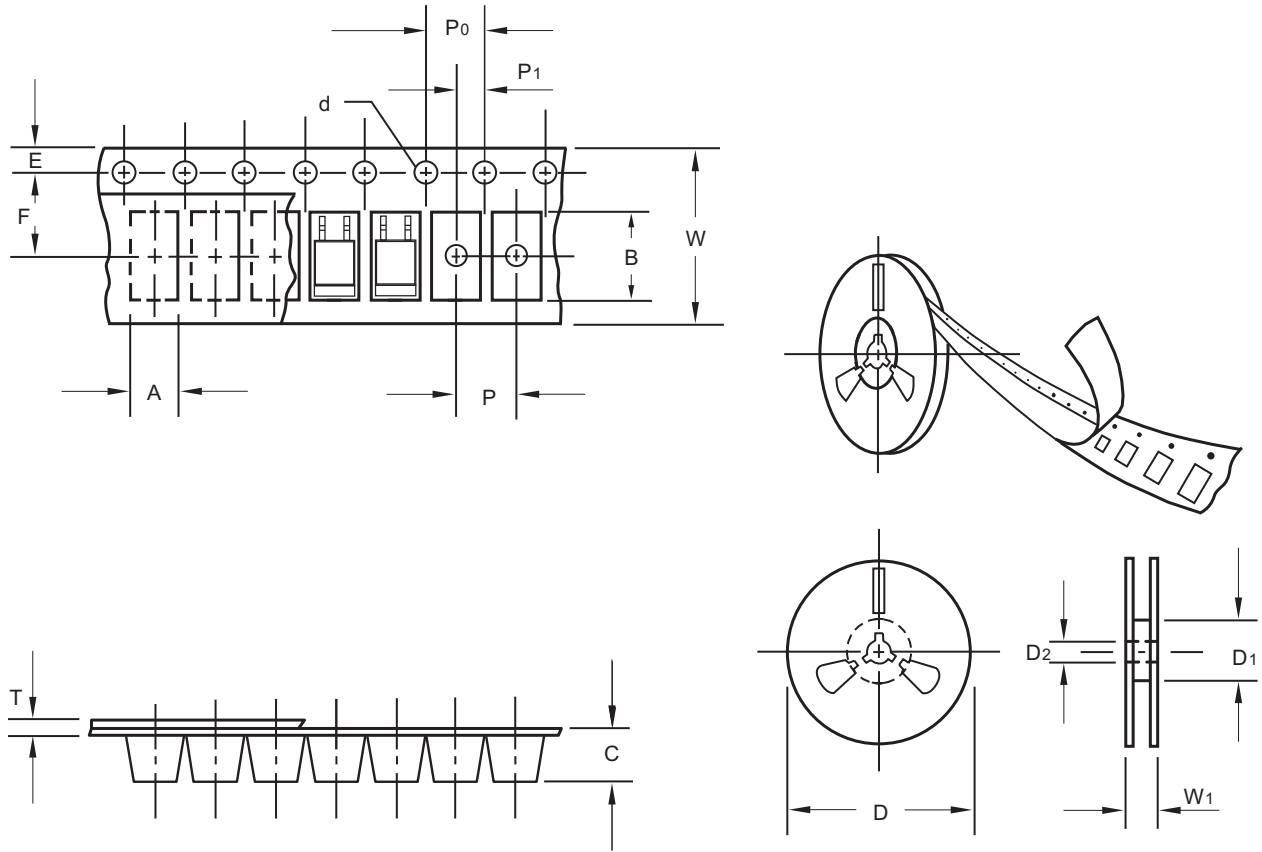


PACKAGE	D2PAK
C	0.374(9.50)
E	0.098(2.50)
L	0.665(16.90)
X1	0.425(10.80)
X2	0.071(1.80)
Y1	0.449(11.40)
Y2	0.138(3.50)

Dimensions in inches and (millimeters)

# SGFM101C-D2 THRU SGFM108C-D2

## Packing information



unit:mm

Item	Symbol	Tolerance	D2PAK
Carrier width	A	0.1	10.70
Carrier length	B	0.1	16.30
Carrier depth	C	0.1	5.10
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D <sub>1</sub>	min	50.00
7" Reel outside diameter	D	2.0	-
7" Reel inner diameter	D <sub>1</sub>	min	-
Feed hole diameter	D <sub>2</sub>	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	11.50
Punch hole pitch	P	0.1	16.00
Sprocket hole pitch	P <sub>0</sub>	0.1	4.00
Embossment center	P <sub>1</sub>	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	24.00
Reel width	W <sub>1</sub>	1.0	30.00

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

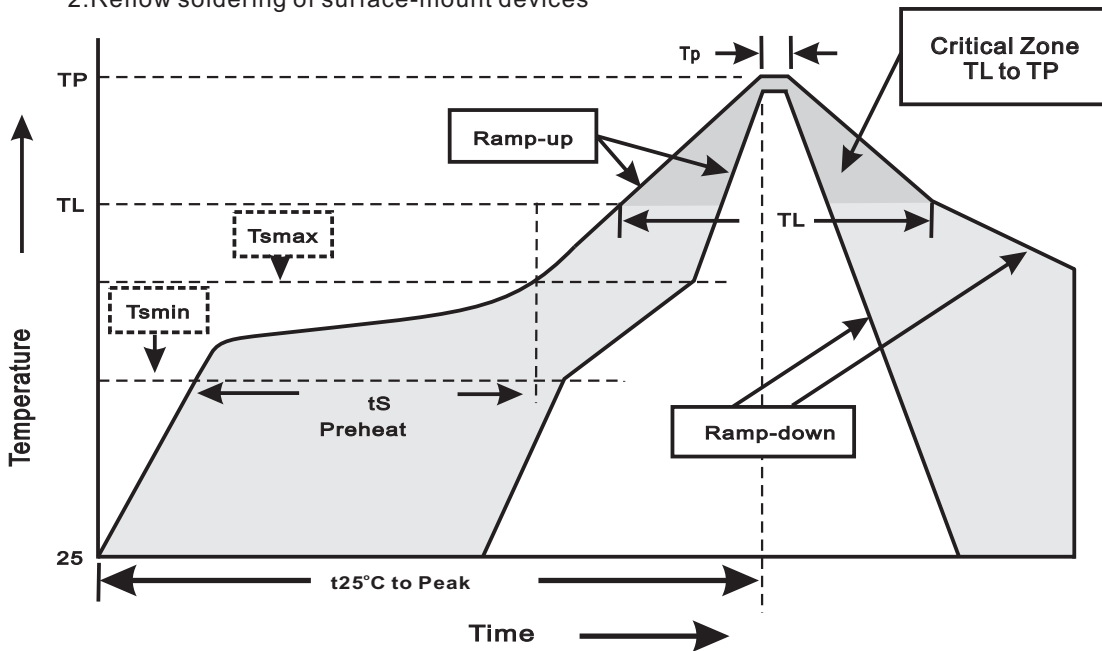
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## Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
D2PAK/TO-263	13"	800	16.0	800	337*337*37	330	350*330*360	6,400	15.0

## Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



### 3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T <sub>L</sub> to T <sub>P</sub> )	<3°C/sec
Preheat -Temperature Min(T <sub>smmin</sub> ) -Temperature Max(T <sub>smmax</sub> ) -Time(min to max)(t <sub>s</sub> )	150°C 200°C 60~120sec
T <sub>smmax</sub> to T <sub>L</sub> -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T <sub>L</sub> ) -Time(t <sub>L</sub> )	217°C 60~260sec
Peak Temperature(T <sub>P</sub> )	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t <sub>p</sub> )	10~30sec
Ramp-down Rate	<3°C/sec
Time 25°C to Peak Temperature	<6minutes

## High reliability test capabilities

Item Test	Conditions	Reference
1. Solder Resistance	at $260\pm 5^{\circ}\text{C}$ for $10\pm 2\text{sec}$ . immerse body into solder $1/16''\pm 1/32''$	MIL-STD-750D METHOD-2031
2. Solderability	at $245\pm 5^{\circ}\text{C}$ for 5 sec.	MIL-STD-202F METHOD-208
3. High Temperature Reverse Bias	$V_R=80\%$ rate at $T_J=150^{\circ}\text{C}$ for 168 hrs.	MIL-STD-750D METHOD-1038
4. Forward Operation Life	Rated average rectifier current at $T_A=25^{\circ}\text{C}$ for 500hrs.	MIL-STD-750D METHOD-1027
5. Intermittent Operation Life	$T_A = 25^{\circ}\text{C}$ , $I_F = I_o$ On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles.	MIL-STD-750D METHOD-1036
6. Pressure Cooker	$15P_{SIG}$ at $T_A=121^{\circ}\text{C}$ for 4 hrs.	JESD22-A102
7. Temperature Cycling	$-55^{\circ}\text{C}$ to $+125^{\circ}\text{C}$ dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
8. Forward Surge	8.3ms single half sine-wave , one surge.	MIL-STD-750D METHOD-4066-2
9. Humidity	at $T_A=85^{\circ}\text{C}$ , RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
10. High Temperature Storage Life	at $175^{\circ}\text{C}$ for 1000 hrs.	MIL-STD-750D METHOD-1031